

## PATENT APPLICATION

ED STATES PATENT AND TRADEMARK OFFICE Applicants:

Yogesh B. Gianchandani,

Date: March 19, 2001

Chester G. Wilson

Docket No.: 032026:0485

Serial No.:

09/686,259

Filed:

October 11, 2000

Group Art Unit: 1765

For:

METHOD AND APPARATUS FOR ETCHING AND DEPOSITION

**USING MICRO-PLASMAS** 

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, U.S. Patent and Trademark Office, Washington, D.C. 20231 on

Harry C. Engstrom (Name of applicant, assignee or Registered Representative) gnature) March 19, 2001 (Date of Signature)

# SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents U.S. Patent and Trademark Office Washington, D.C. 20231

Dear Sir:

With respect to the examination of the above-referenced application, applicants cite the following documents, copies of which are enclosed. These documents are also listed on an accompanying Form PTO-1449.

### U.S. PATENTS

Inventor(s)	Patent No.	Issue Date
Larson, et al.	5,302,237	April 12, 1994
Bollinger, et al.	5,688,415	Nov. 18, 1997

## FOREIGN PATENT DOCUMENTS

Germany

DE 19826418A1

30 December 1999

## OTHER DOCUMENTS

Q.Y. Tong and U. Gosele, <u>Semiconductor Wafer Bonding: Science and Technology</u> (Book), John Wiley & Sons, Inc., 1998, pp. 138-139.

B. Pashaie, et al., "Experimental Investigation of Microdischarges in a Dielectric-Barrier Discharge," IEEE Trans. on Plasma Science, Vol. 27, No. 1, February 1999, pp. 22-23.

### **REMARKS**

The above-referenced United States patents and the published German patent application were cited in the International Search Report issued by the European Patent Office on February 16, 2001 on a Patent Cooperation Treaty application corresponding to the present U.S. application. A copy of the International Search Report is also enclosed. The section of the book by Q.Y. Tong and U. Gosele was previously cited without the date of publication, which is provided in the citation above. The paper by B. Pashaie, et al. discusses microdischarges.

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No Office Action has been received by Applicants at this time. It is thus requested that the foregoing documents be considered during examination of the above-referenced application and be specifically made of record therein.

Respectfully submitted,

Harry C. Engstrom, Reg. No. 26,876

Attorney for Applicants

Foley & Lardner

150 East Gilman Street

Post Office Box 1497

Madison, Wisconsin 53701-1497

(608) 258-4207

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